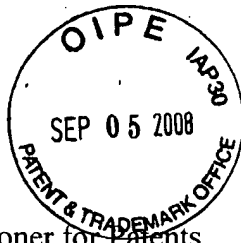


September 2, 2008



To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/802,563 03/17/04

Hong Yu Yu et al

“A THERMAL ROBUST SEMICONDUCTOR  
DEVICE USING HFN AS METAL GATE  
ELECTRODE AND THE MANUFACTURING  
PROCESS THEREOF”

Grp. Art Unit: 2823

SU C. KIM


## RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Office Action dated April 3, 2008, please amend the above-identified application for patent as follows:

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on September 3, 2008.

Stephen B. Ackerman, Reg. No. 37,761  
Signature   
Date September 3, 2008

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 10 of this paper.